

Texas Instruments' Ultra-Thin Module Enables Card Manufacturers To Improve Yields and Offer Range of Complex and Colorful Contactless Payment Products

To help card-issuing banks differentiate their brand in order to stay “top of wallet” with their customers, Texas Instruments now offers an ultra-thin module for contactless payment applications. Now 26 percent thinner than conventional packaged contactless chip offerings, the new ultra-thin module enables card manufacturers to produce an increasing array of colorful and distinctive products with higher yields as a result of causing fewer visual defects than thicker chip modules.

Using the new TI ultra-thin module, the industry’s thinnest contactless payment chip, card manufacturers can help address banks concerns. The TI ultra-thin module enables the creation of a thinner PVC pre-laminate sheets for the contactless layer, which allows the card manufacturer to print the card’s artwork on thicker print stock while keeping overall card thickness the same, maintaining the ISO standard of 680-840um (26.8-33.1 mil). This is important because the ability to print on sturdier and thicker print stock enables the creation of more colorful and graphic-rich card designs.

Another benefit to the issuer and card manufacturer is the ability to maximize yield during the standard card manufacturing production processes. Complex card designs require multiple passes through a printing press, and thinner print stock has a tough time surviving that with high yields. Using the TI ultra-thin module solves that problem by giving card manufacturers the ability to use the more durable, thicker print stock.

TI’s ultra-thin module operates at extremely low power, delivers a fast transaction speed (typically 120 milliseconds) and is developed with a highly sensitive radio frequency chip to enable a successful transaction the first time a customer taps the card to the payment reader. The module and payment application software operate in dynamic CVC transaction authorization mode which offers issuers the highest level of security available.

The Ultra-Thin Module packaging will be available in MasterCard PayPass™ and other contactless payment products. For more information on TI’s ultra-thin module and its contactless payment technology and applications, visit www.ti.com/contactless, e-mail ultra-thin@ti.com, or call 1-800-962-7343.